

## Product Summary

$V_{(BR)DSS}$	$R_{DS(on)MAX}$	$I_D$
80V	1.05mΩ@10V	445A

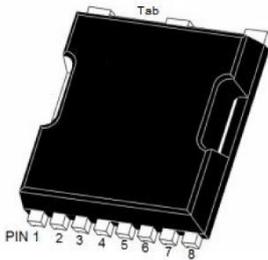
## Feature

- Excellent package for heat dissipation
- High density cell design for low  $R_{DS(on)}$
- Suffix "-Q1" for AEC-Q101

## Application

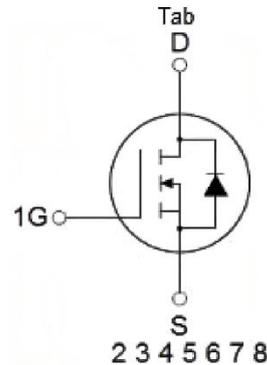
- Power switching application
- Uninterruptible power supply
- DC-DC convertor

## Package

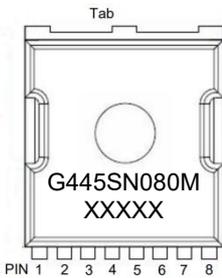


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## Circuit diagram



## Marking



### Absolute maximum ratings ( $T_C=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	80	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current <sup>1,3)</sup> ( $V_{GS} = 10\text{V}$ , Chip limitation)	$I_D$	445	A
Continuous Drain Current <sup>1,3)</sup> ( $V_{GS} = 10\text{V}$ , $T_C = 100^\circ\text{C}$ )	$I_D(100^\circ\text{C})$	314	A
Pulsed Drain Current ( $t_p \leq 10\mu\text{s}$ )	$I_{DM}$	1780	A
Single Pulse Avalanche Energy <sup>2)</sup>	$E_{AS}$	2401	mJ
Power Dissipation <sup>1,3)</sup>	$P_D$	416	W
Thermal Resistance Junction to Case	$R_{\theta JC}$	0.36	$^\circ\text{C}/\text{W}$
Operating Junction Temperature	$T_J$	$-55 \sim +175$	$^\circ\text{C}$
Storage Temperature Range	$T_{STG}$	$-55 \sim +175$	$^\circ\text{C}$

### Electrical characteristics ( $T_J=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0\text{V}$ , $I_D = 1\text{mA}$	80			V
Zero gate voltage drain current	$I_{DSS}$	$V_{DS} = 80\text{V}$ , $V_{GS} = 0\text{V}$			1	$\mu\text{A}$
Gate-body leakage current	$I_{GSS}$	$V_{DS} = 0\text{V}$ , $V_{GS} = \pm 20\text{V}$			$\pm 100$	nA
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$ , $I_D = 250\mu\text{A}$	2.2	3	3.8	V
Drain-source on-resistance	$R_{DS(on)}$	$V_{GS} = 10\text{V}$ , $I_D = 50\text{A}$		0.79	1.05	m $\Omega$
<b>Dynamic characteristics<sup>4)</sup></b>						
Input Capacitance	$C_{iss}$	$V_{DS} = 40\text{V}$ , $V_{GS} = 0\text{V}$ $f = 1\text{MHz}$		13030		pF
Output Capacitance	$C_{oss}$			3930		
Reverse Transfer Capacitance	$C_{rss}$			130		
Total Gate Charge	$Q_g$	$V_{DS} = 40\text{V}$ , $V_{GS} = 10\text{V}$ , $I_D = 50\text{A}$		236.7		nC
Gate-Source Charge	$Q_{gs}$			53.6		
Gate-Drain Charge	$Q_{gd}$			79.4		
Turn-on delay time	$t_{d(on)}$	$V_{DS} = 40\text{V}$ , $V_{GS} = 10\text{V}$ , $I_D = 50\text{A}$ $R_G = 3\Omega$		29.1		nS
Turn-on rise time	$t_r$			152.9		
Turn-off delay time	$t_{d(off)}$			163.3		
Turn-off fall time	$t_f$			161.3		
<b>Source-Drain Diode characteristics</b>						
Diode Forward Current	$I_S$	$T_C = 25^\circ\text{C}$			445	A
Diode Forward voltage	$V_{SD}$	$V_{GS} = 0\text{V}$ , $I_S = 50\text{A}$			1.2	V
Reverse Recovery Time	$T_{rr}$	$V_{GS} = 0\text{V}$ , $V_R = 40\text{V}$ , $I_F = 50\text{A}$ $di/dt = -100\text{A}/\mu\text{s}$		87.7		nS
Reverse Recovery Charge	$Q_{rr}$			153.7		nC

Notes:

- 1) The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
- 2) The test condition is  $T_J = 25^\circ\text{C}$ ,  $V_G = 10\text{V}$ ,  $L = 2\text{mH}$ ,  $R_G = 25\Omega$ ,  $I_S = 49\text{A}$ .
- 3) Thermal resistance from junction to soldering point (on the exposed drain pad).
- 4) Guaranteed by design, not subject to production.

## Typical Characteristics

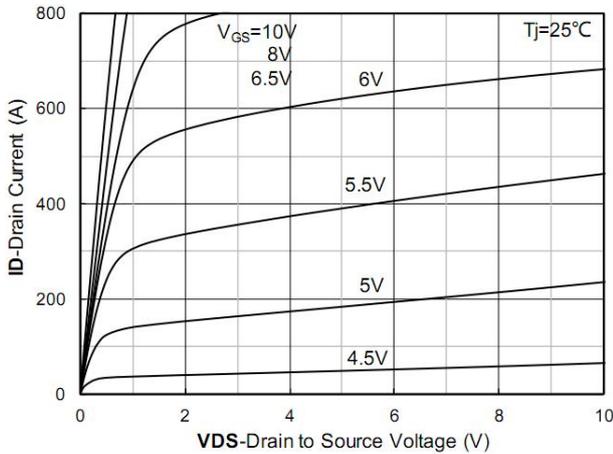


Figure 1. Output Characteristics; typical values

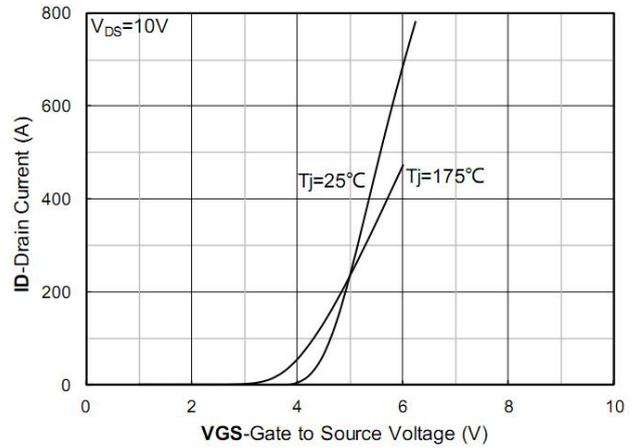


Figure 2. Transfer Characteristics; typical values

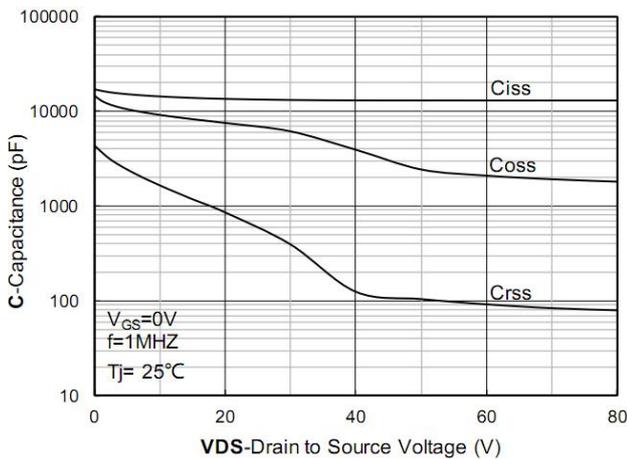


Figure 3. Capacitance Characteristics; typical values

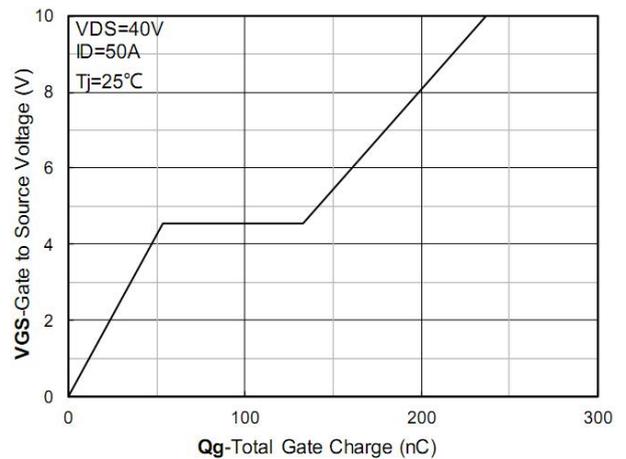


Figure 4. Gate Charge; typical values

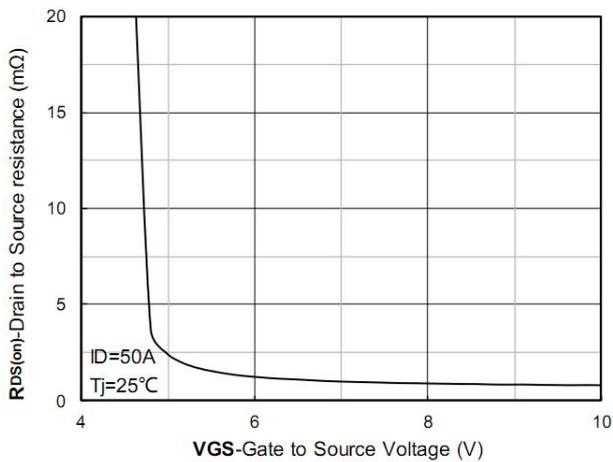


Figure 5. On-Resistance vs. Gate to Source Voltage;

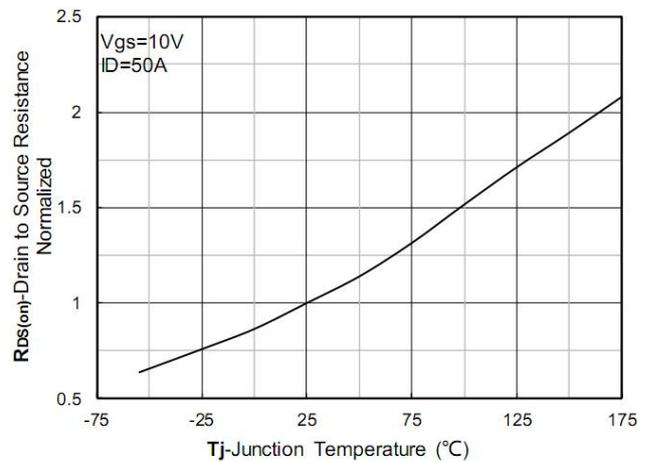


Figure 6. Normalized On-Resistance

## Typical Characteristics

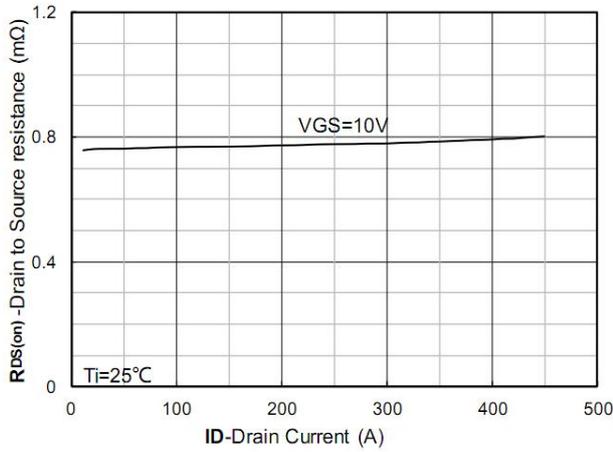


Figure 7.  $R_{DS(on)}$  vs. Drain Current; typical values

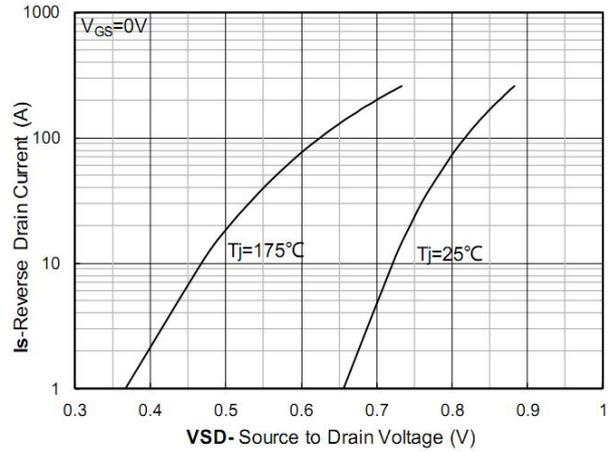


Figure 8. Forward characteristics of reverse diode;

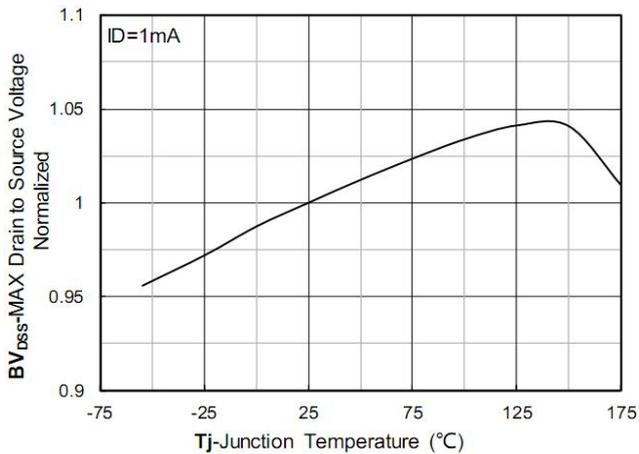


Figure 9. Normalized breakdown voltage

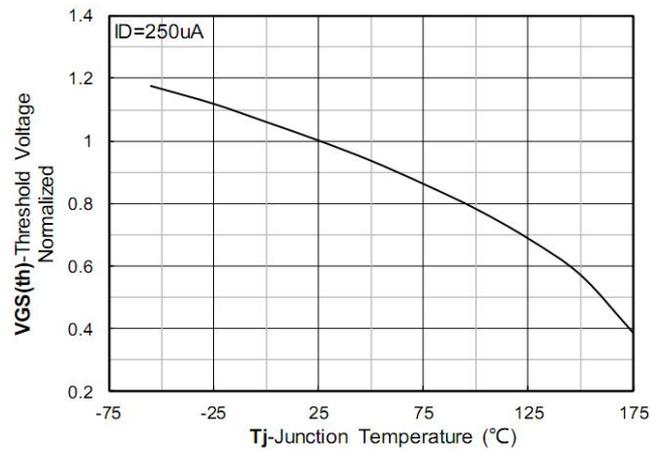


Figure 10. Normalized Threshold voltage

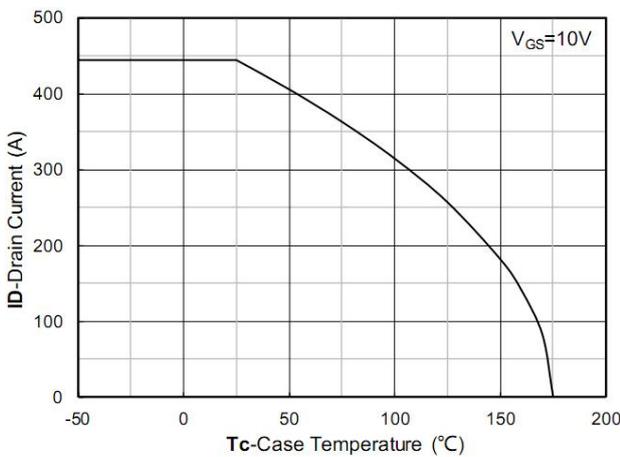


Figure 11. Current dissipation

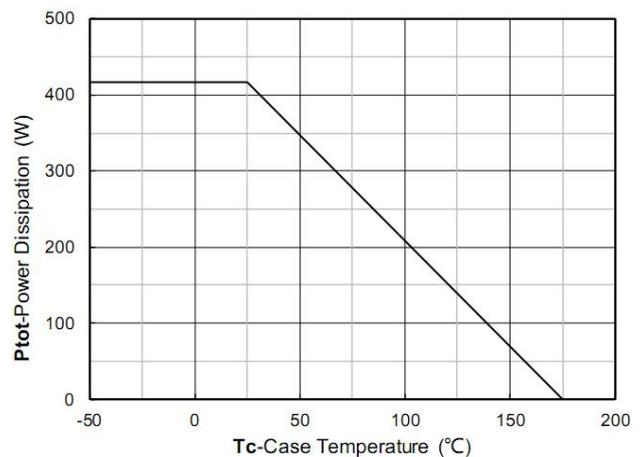


Figure 12. Power dissipation

## Typical Characteristics

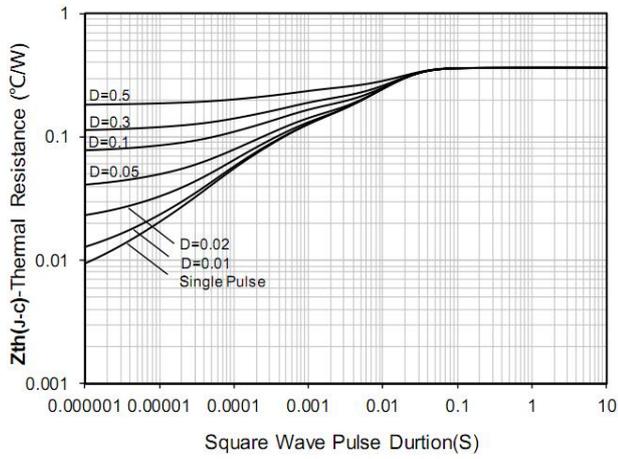


Figure 13. Maximum Transient Thermal Impedance

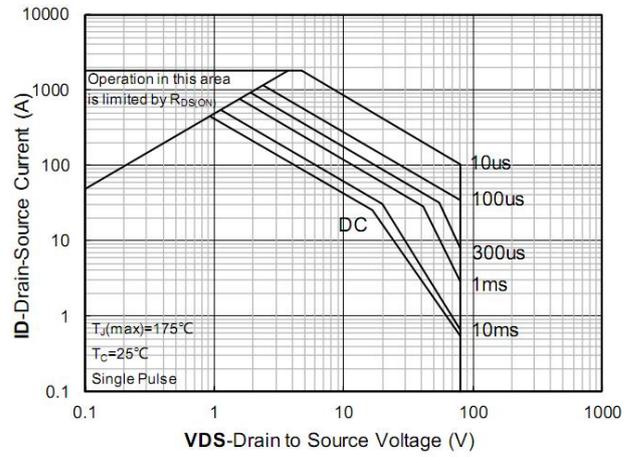
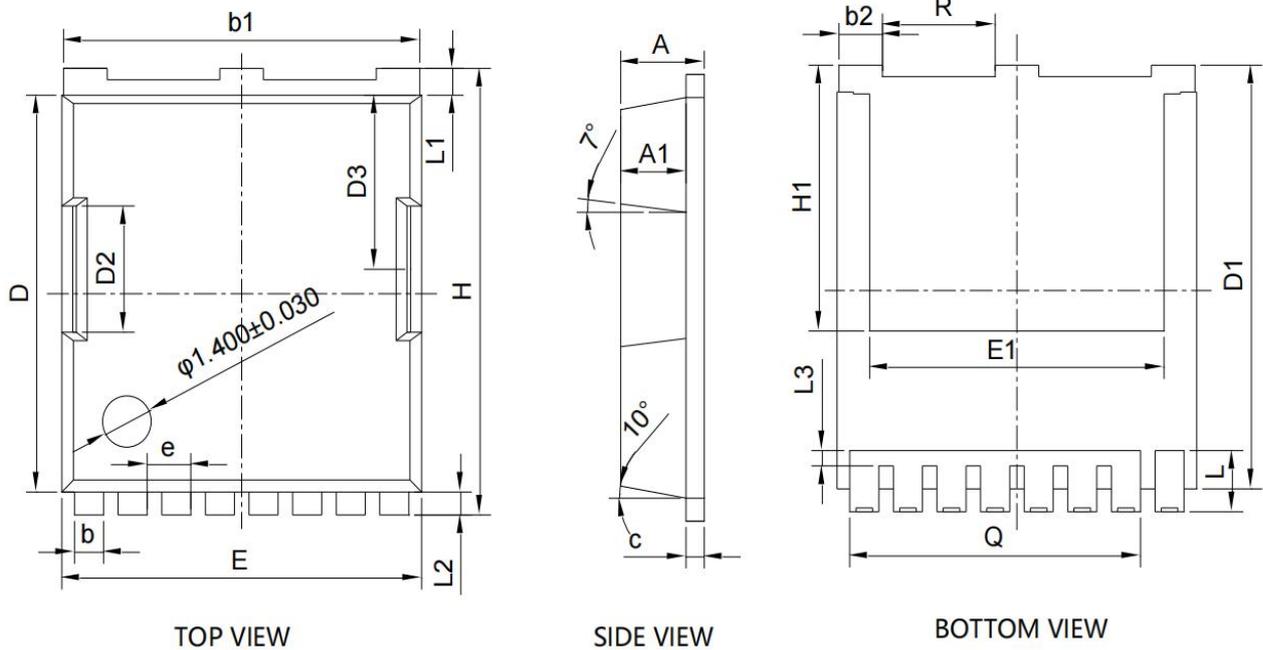


Figure 14. Safe Operation Area

### TOLL Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	1.700	1.900	0.067	0.075
b	0.700	0.900	0.028	0.035
b1	9.700	9.900	0.382	0.390
b2	1.100	1.300	0.043	0.051
c	0.400	0.600	0.016	0.024
D	10.280	10.480	0.405	0.413
D1	10.980	11.180	0.432	0.440
D2	3.200	3.400	0.126	0.134
D3	4.450	4.650	0.175	0.183
E	9.800	10.000	0.386	0.394
E1	8.000	8.200	0.315	0.323
e	1.200 BSC.		0.047 BSC.	
H	11.580	11.780	0.456	0.464
H1	6.950 BSC.		0.274 BSC.	
L	1.500	1.700	0.059	0.067
L1	0.600	0.800	0.024	0.031
L2	0.500	0.700	0.020	0.028
L3	0.300	0.500	0.012	0.020
Q	8.000 REF.		0.315 REF.	
R	3.000	3.200	0.118	0.126